CLAIMS

[Claim 1]

A transfer method comprising the steps of:

(a) providing a paste to a first setting section, which is a table;

(b) providing an electronic component to a second setting section;

(c) providing the first setting section and the second setting section by having a space there between such that the paste and the electronic component are facing each other;

(d) warping the second setting section, which is composed of an elastic sheet, so that the paste and the electronic component are close to each other, and pressing the electronic component to the paste; and

(e) separating the electronic component from the paste that has been provided to the first setting section and adhering a portion of the paste to the electronic component.

[Claim 2]

The transfer method according to claim 1,

wherein, in the step (a), a thickness of the paste is equalized by using a squeegee.

[Claim 3]

The transfer method according to claim 1 or 2,

wherein, in the step (b), a plurality of the electronic components are provided to the second setting section, and

in the step (d), the plurality of the electronic components

are collectively pressed to the paste.

[Claim 4]

The transfer method according to any one of claims 1-3, wherein, in the step (a), the paste is provided to a first surface of the first setting section,

in the step (b), the electronic component is provided to a second surface of the second setting section, and

in the step (c), the first setting section and the second setting section are provided with the space such that the first surface of the first setting section and the second surface of the second setting section are parallel to each other.

[Claim 5]

The transfer method according to any one of claims 1-4, wherein, before performing the step (d), the sheet is made flat, and

in the step (d), the flat sheet is warped by pressing the sheet with a pressing section, which has an end surface and whose width is gradually reduced toward the end surface, in a state where the end surface is parallel to the flat sheet.

[Claim 6]

The transfer method according to any one of claims 1-5, wherein,

in the step (d), the sheet is warped, toward the paste, from one side thereof, which is the opposite side to the side to which the electronic component has been provided.

[Claim 7]

The transfer method according to claim 6,

wherein temperature of the paste provided to the table is maintained by a temperature control means, which is provided to the table.

[Claim 8]

A mounting method including the transfer method of any one of claims 1-7,

wherein, after performing the step (e), the electronic component is mounted onto a substrate with the portion of the paste.